

Missing packaging material parameters - Data collection

Objectives

- Survey of the existing MEMS packaging material parameters
- Identification of the missing parameters
- Recommendation for the WP3 group to orient their material parameter collecting activity

Partners involved and roles

- BUTE: collection activity
- All WP4 partners: evaluation

Summary of results

- The present and past activity of the WP3 group to collect material parameters' data significantly covers the needs of MEMS packaging.
- Nevertheless some important materials used in MEMS packaging are missing from this activity
- Recommendations: materials that should be researched by WP3 community:
 - Metals: Ag, Fe/stainless steel
 - Substrates: ceramics: Al₂O₃, BeO, and (Pyrex) glasses
 - Protective films: Parylene,
 - Mask materials: Silicone resin, Epoxy resin, PMMA, PTFE, PVDF

Offer to industry

- To be specified

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Project status, date:

Phase 1: finished; Phase 2: to be defined